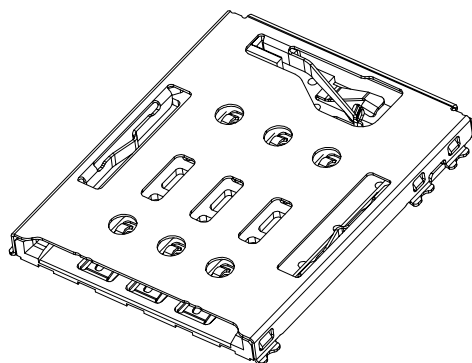
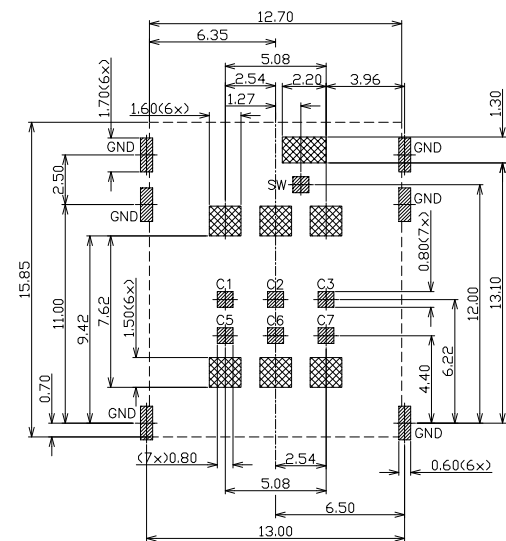
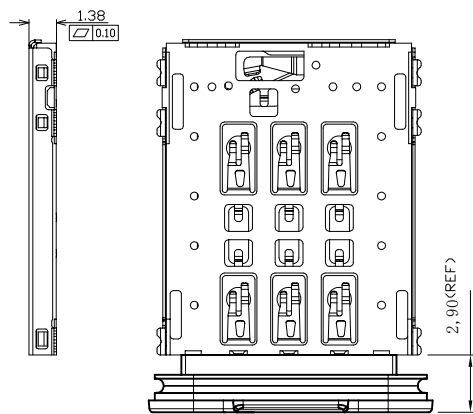
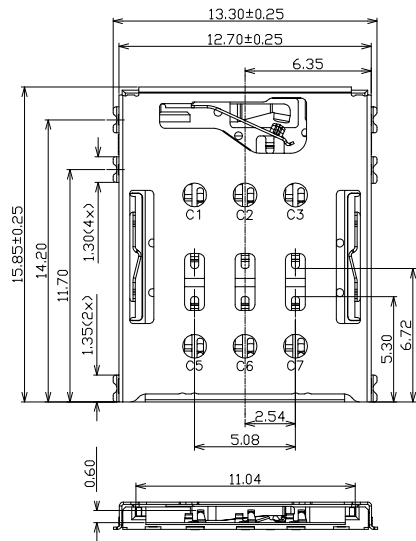


REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2019/11/29



TECHNICAL CHARACTERISTICS

- General Characteristics
 Dimensions: 12.85L X 17.20W X 1.38H mm
 TRAY MATING FORCE: 2~10N
 TRAY UNMATING FORCE: 4~10N
 Durability: 1,500 cycles min.
- Electrical Characteristics
 Contact resistance: 50mΩ typical,
 100mΩ Max
 Insulation resistance: >1000M/500V DC
- Solderability
 Vapor phase: 215°C, 30sec. Max
 IR reflow: 260°C, 5sec. Max
 Manual soldering: 370°C, 3sec. Max
- Environmental Characteristics
 Operating temperature: -40°C ~ +85°C
 Operating humidity: 10% ~ +95%RH

RECOMMENDED P.C.B LAYOUT
 COMPONENT SIDE (TOLERANCE ±0.05)

- PAD AREA
- KEEP AREA
- NO PATTERN AND VIA HOLE IN THIS AREA

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	6	Copper Alloy	Contact area: Gold plated
3	SWITCH	1	Copper Alloy	Contact area: Gold plated
4	SHELL	1	Stainless Steel	Solder area: Gold plated

GENERAL TOLERANCE		DWG NO.	JYSA0525-009	APPD:	WIND	Scale	1:1
X.±0.45	x.±5'	Title	1.38H NANO SIM CARD 7PIN	CHKD:		UNIT	mm
.X±0.35	.x'±2'			DR:			
.XX±0.25	.xx'±1'	Part NO.	JYS-SIM138-189	Date	2019/11/29		
.XXX±0.15	.xxx'±0.5'						
SHEET	1/1			Shenzhen JYSCONN Electronics Co., LTD.			

CIRCUIT DIAGRAM FOR DETECT SWITCHES

